



A METHOD FOR EMBEDDING AN AIR DIELECTRIC TRANSMISSION LINE IN A PRINTED WIRING BOARD(PCB).

ABSTRACT

An air dielectric printed circuit board fabrication method is disclosed based on the principles of suspended substrate transmission lines as used in microwave assemblies.

The transmission line conductor is on a thin dielectric layer suspended in air between two conductive planes. The ground in the area around the transmission line may be cut back either by milling or by photo-etching to preclude shorting the transmission line.



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